



BAS40LP

SURFACE MOUNT SCHOTTKY BARRIER DIODE

Features

- Low Forward Voltage Drop
- Fast Switching
- Ultra-Small Leadless Surface Mount Package
- PN Junction Guard Ring for Transient and ESD Protection
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: X1-DFN1006-2
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Marking Information
- Terminals: Finish NiPdAu Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208^{@4}
- Weight: 0.001 grams (Approximate)

X1-DFN1006-2







Bottom View

Ordering Information (Note 4)

Part Number	Case	Packaging
BAS40LP-7	X1-DFN1006-2	3,000/Tape & Reel
BAS40LP-7B	X1-DFN1006-2	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

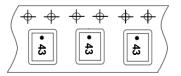
Marking Information



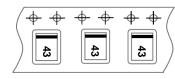
From date code 1527 (YYWW), this changes to:



Top View Dot Denotes Cathode Side



Top View Bar Denotes Cathode Side



43 = Part Marking Code



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _R WM V _R	40	٧
Forward Continuous Current	I _{FM}	200	mA
Repetitive Peak Forward Current (Note 6)	I _{FRM}	800	mA
Non-Repetitive Peak Forward Surge Current @ t _p = 1.0s (Note 7)	I _{FSM}	1,000	mA

Thermal Characteristics

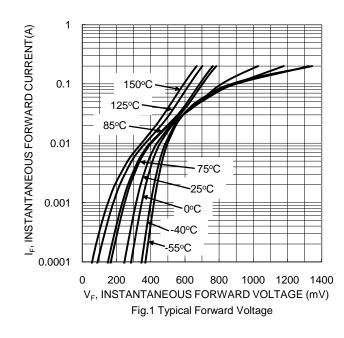
Characteristic	Symbol	Value	Unit
Power Dissipation	P_{D}	250	mW
Typical Thermal Resistance, Junction to Ambient (Note 8)	R _{0JA}	400	°C/W
Operating Temperature Range	T_J	-55 to +150	°C
Storage Temperature Range	T _{STG}	-65 to +150	°C

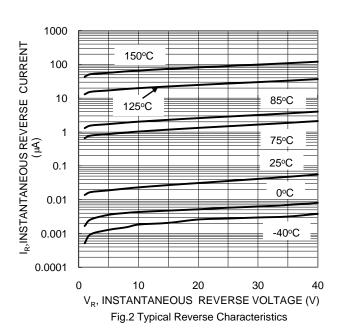
Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 5)	V_R	40	_	_	V	$I_R = 10\mu A$
Forward Voltage (Note 5)	V _F		_	380 1,000		$t_p < 300 \mu s$, $I_F = 1.0 mA$ $t_p < 300 \mu s$, $I_F = 40 mA$
Reverse Leakage Current (Note 5)	I _R	_	20	200	nA	$t_p < 300 \mu s, V_R = 30 V$
Total Capacitance	C _T	_	2.3	5.0	рF	$V_R = 0V$, $f = 1.0MHz$
Reverse Recovery Time	t _{RR}		_	5.0	ns	$\begin{split} I_F = \ I_R = 10 \text{mA to } I_R = 1.0 \text{mA}, \\ R_L = 100 \Omega \end{split}$

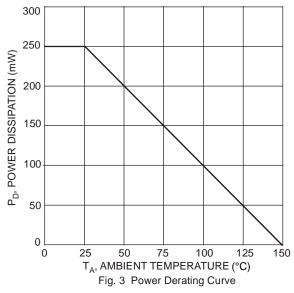
Notes:

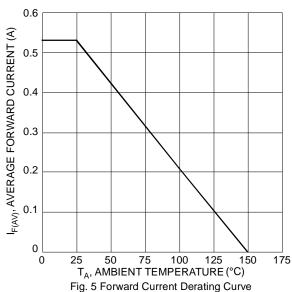
- 5. Short duration pulse test used to minimize self-heating effect.
- 6. Repetitive peak forward current was tested with $t_p \le 1$ s and $\partial \le 0.8$ square wave.
- 7. Non-repetitive peak forward current was tested with t_p = 1s square wave.
 8. 1*MRP FR-4 PC board 2oz.Copper, minimum recommended pad layout per http://www.diodes.com/package-outlines.html.











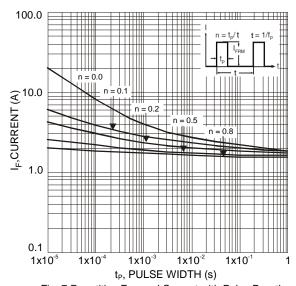
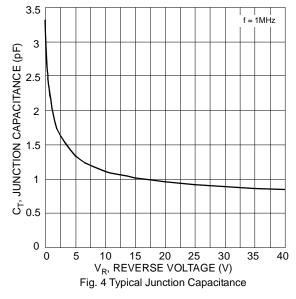
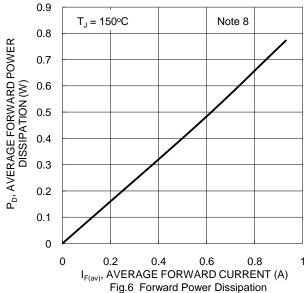


Fig. 7 Repetitive Forward Current with Pulse Duration



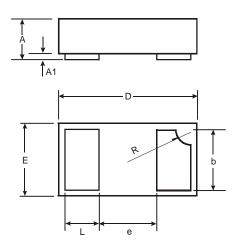




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

X1-DFN1006-2

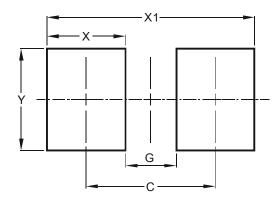


X1-DFN1006-2					
Dim	Min	Max	Тур		
Α	0.47	0.53	0.50		
A1	0	0.05	0.03		
b	0.45	0.55	0.50		
D	0.95	1.075	1.00		
Е	0.55	0.675	0.60		
е	-	-	0.40		
٦	0.20	0.30	0.25		
R	0.05	0.15	0.10		
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X1-DFN1006-2



Dimensions	Value (in mm)
С	0.70
G	0.30
Х	0.40
X1	1.10
Υ	0.70



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